ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22647X
Issue Date: 21 June 2019

Title of Change:	EMC Change for the devices which use Samsung SDI EMC-For SPM5.
Proposed first ship date:	28 September 2019 *or earlier upon customer approval.*
Contact information:	Contact your local ON Semiconductor Sales Office or <Xingquan.Fang@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <Xingquan.Fang@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Lake.Wang@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	The supplier of Mold Compound is changed from Samsung SDI(EMC type is SL7300HPM) to KCC (EMC type is KTMC3100GP3)
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☐ Test Change ☐ Other ________

Change Sub-Category(s):

☐ Manufacturing Site Addition
☐ Manufacturing Site Transfer
☐ Manufacturing Process Change

☑ Material Change
☐ Product specific change

☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________

Sites Affected:	ON Semiconductor Sites: ON Suzhou, China	External Foundry/Subcon Sites: None

Description and Purpose:

The supplier of Mold compound Samsung SDI decided to cease mold compound business from September 1, 2019.

	Before Change Description	After Change Description
Mold Compound	SL7300HPM; Supplier: Samsung SDI	KTMC3100GP3; Supplier: KCC

Reliability Data Summary:

QV DEVICE NAME: FSB50550US
RMS: U56348
PACKAGE: SPM5

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Tj = 150C for device, bias = 80% of max rated	1008 hrs	0/60
TC+PC	JESD22-A104	Ta = -40°C to +125°C	500 cyc	0/60
H3TRB+PC	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 hrs	0/60
Preconditioning(PC)	J-STD-020 , JESD22-A113	MSL 3 @ 260°C	192hr	0/60

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal.**

Part Number	Qualification Vehicle
FSB50550US	FSB50550US
FSB50250US	
FSB50450S	
FSB50450US	
FSB50825US	
FSB52006S	